



[Document Name] : Abstract

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[Object] A bump forming apparatus which carries out a temperature control of a type different from the conventional art in forming bumps to a semiconductor wafer, and a bump formation method executed by the bump forming apparatus are provided.

[Construction] A bonding stage 110, a load and transfer device 140 and a control device 180 are comprised, whereby a wafer 202 after having bumps formed thereon which is held by the load and transfer device is disposed to above the bonding stage through control by the control device, so that a temperature drop of the wafer is controlled. Accordingly, generation of troubles such as a crack because of a thermal stress and the like can be prevented to even compound semiconductor wafers sensitive to a temperature change.

[Selected Figure] Fig. 1